

ABSTRACT OF THE INVENTION

A thermoplastic or thermosetting <sup>curable composition</sup> adhesive for bonding an electronic component to a substrate in which the adhesive is cured in situ from a curable

- 5 ~~composition~~ comprises one or more poly- or mono-functional maleimide compounds, or one or more poly- or mono-functional vinyl compounds other than maleimide compounds, or a combination of maleimide and vinyl compounds, a curing initiator and optionally, one or more fillers.

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03/30/01

062190-5429E50